

## Electronic Patent Application Fee Transmittal

Application Number:	10736618
Filing Date:	17-Dec-2003
Title of Invention:	SURFACE MOUNT CHIP PACKAGE
First Named Inventor/Applicant Name:	Yoshihiro Ohkura
Filer:	Michael J. Scheer/Inga Hildreth
Attorney Docket Number:	X2007.0147

Filed as Large Entity

### Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
-------------	----------	----------	--------	----------------------

Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Utility Appl Issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
Printed copy of patent - no color	8001	10	3	30
<b>Total in USD (\$)</b>				<b>1730</b>